

FQD16N25C

250V N-Channel MOSFET

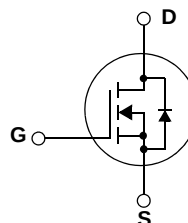
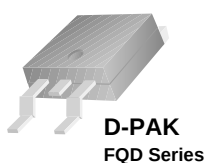
Features

- 16A, 250V, $R_{DS(on)} = 0.27\Omega$ @ $V_{GS} = 10\text{ V}$
- Low gate charge (typical 41 nC)
- Low C_{rss} (typical 68 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supplies and motor controls.



Absolute Maximum Ratings

Symbol	Parameter	FQD16N25C	Units
V_{DSS}	Drain-Source Voltage	250	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	16	A
	- Continuous ($T_C = 100^\circ\text{C}$)	10.1	A
I_{DM}	Drain Current - Pulsed (Note 1)	64	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	432	mJ
I_{AR}	Avalanche Current (Note 1)	16	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	160	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	160	W
	- Derate above 25°C	1.28	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FQD16N25C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.78	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	110	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FQD16N25C	FQD16N25CTM	D-PAK	380mm	16mm	2,500
FQD16N25C	FQD16N25CTF	D-PAK	380mm	16mm	2,000

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units	
Off Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	250	--	--	V	
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	--	0.31	--	V/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 250 V, V _{GS} = 0 V	--	--	10	μA	
		V _{DS} = 200 V, T _C = 125°C	--	--	100	μA	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA	
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA	
On Characteristics							
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0	--	4.0	V	
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 8A	--	0.22	0.27	Ω	
g _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D =8 A (Note 4)	--	10.5	--	S	
Dynamic Characteristics							
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	--	830	1080	pF	
C _{oss}	Output Capacitance		--	170	220	pF	
C _{rss}	Reverse Transfer Capacitance		--	68	89	pF	
Switching Characteristics							
t _{d(on)}	Turn-On Delay Time	V _{DD} = 125 V, I _D = 16A, R _G = 25 Ω	--	15	40	ns	
t _r	Turn-On Rise Time		--	130	270	ns	
t _{d(off)}	Turn-Off Delay Time		(Note 4, 5)	--	135	280	ns
t _f	Turn-Off Fall Time			--	105	220	ns
Q _g	Total Gate Charge	V _{DS} = 200 V, I _D = 16A, V _{GS} = 10 V	--	41	53.5	nC	
Q _{gs}	Gate-Source Charge		(Note 4, 5)	--	5.6	--	nC
Q _{gd}	Gate-Drain Charge	--		22.7	--	nC	
Drain-Source Diode Characteristics and Maximum Ratings							
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	16	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	64	A	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 16 A	--	--	1.5	V	
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 16 A, dI _F / dt = 100 A/μs	--	260	--	ns	
Q _{rr}	Reverse Recovery Charge	(Note 4)	--	2.47	--	μC	

NOTES:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 2.7mH, I_{AS} = 16A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
3. I_{SD} ≤ 16A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C
4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

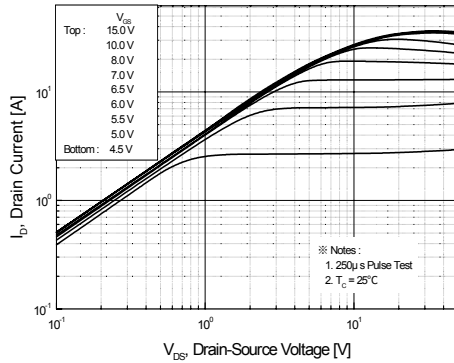


Figure 2. Transfer Characteristics

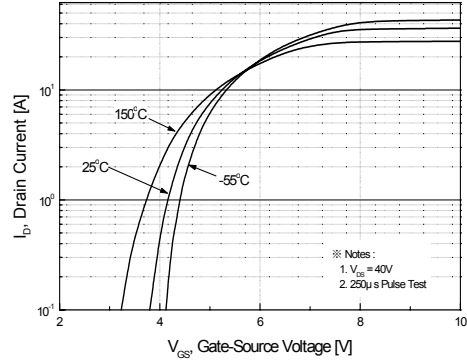


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

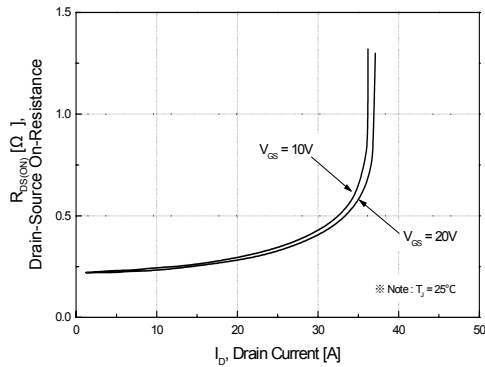


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

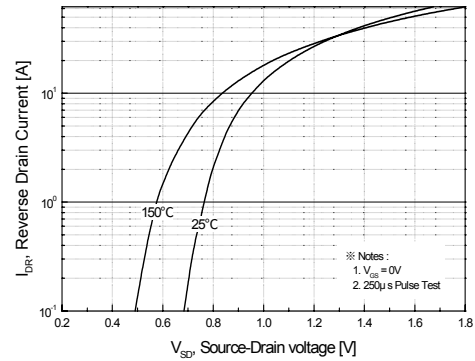


Figure 5. Capacitance Characteristics

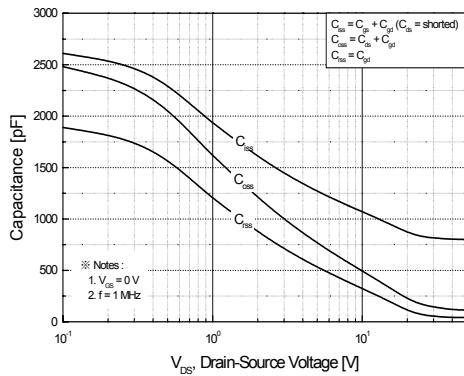
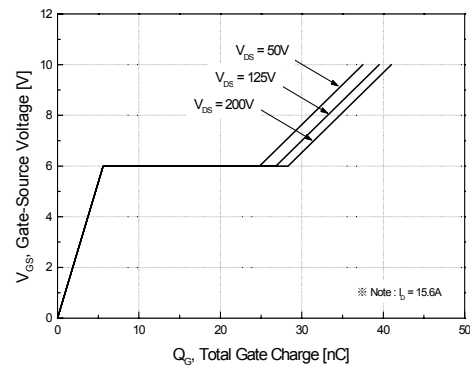


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

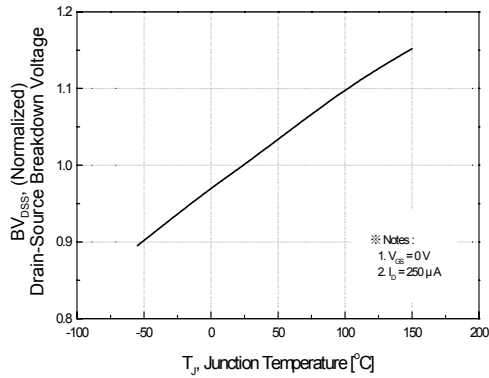


Figure 8. On-Resistance Variation vs. Temperature

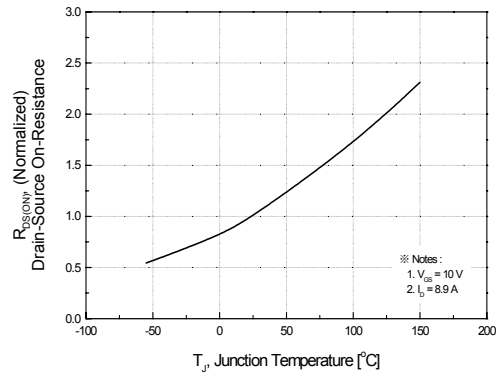


Figure 9. Maximum Safe Operating Area

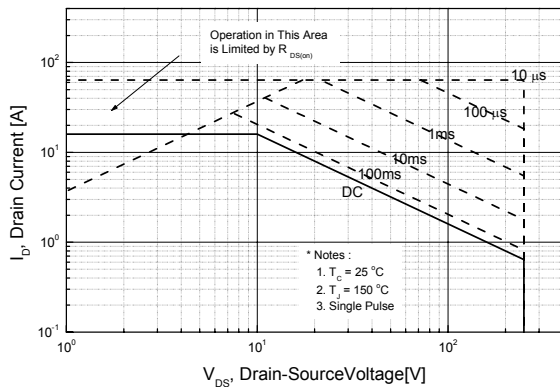


Figure 10. Maximum Drain Current vs. Case Temperature

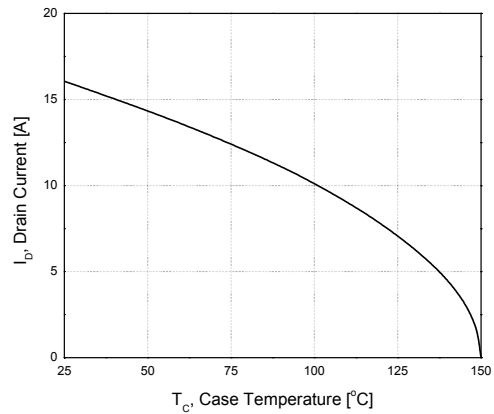
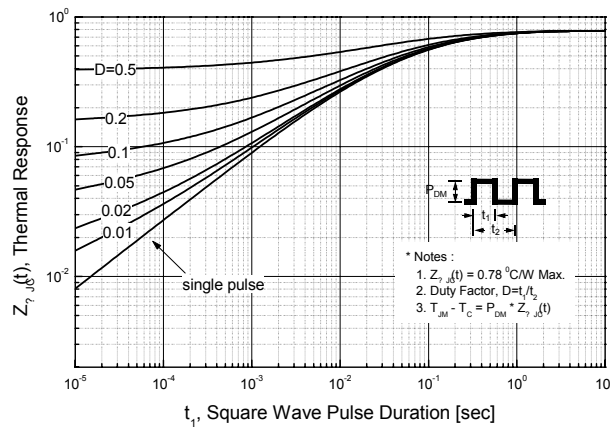
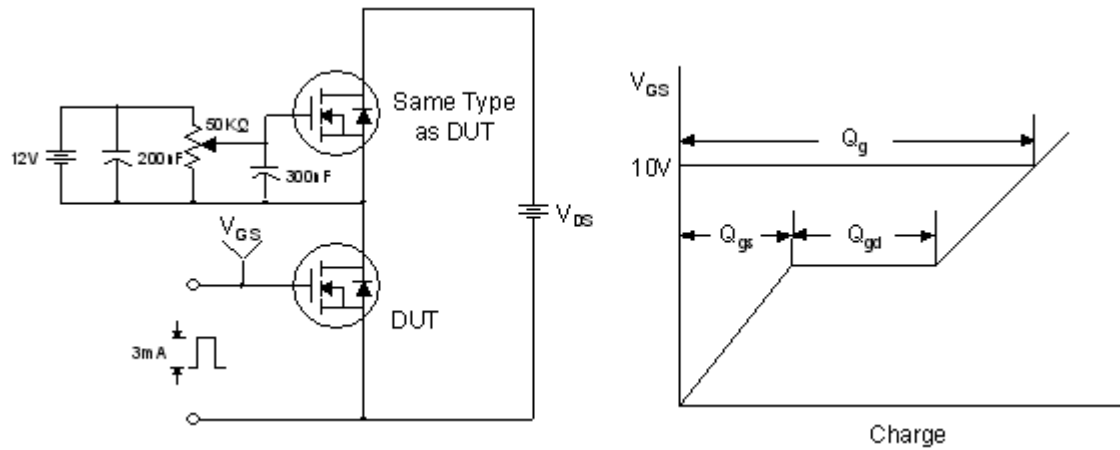


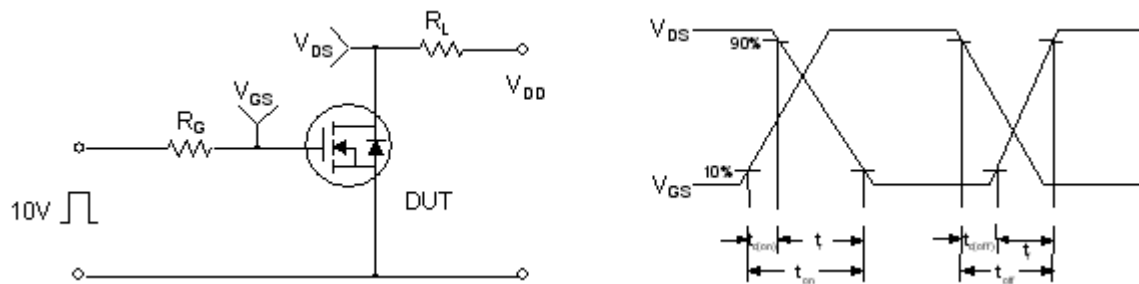
Figure 11. Transient Thermal Response Curve



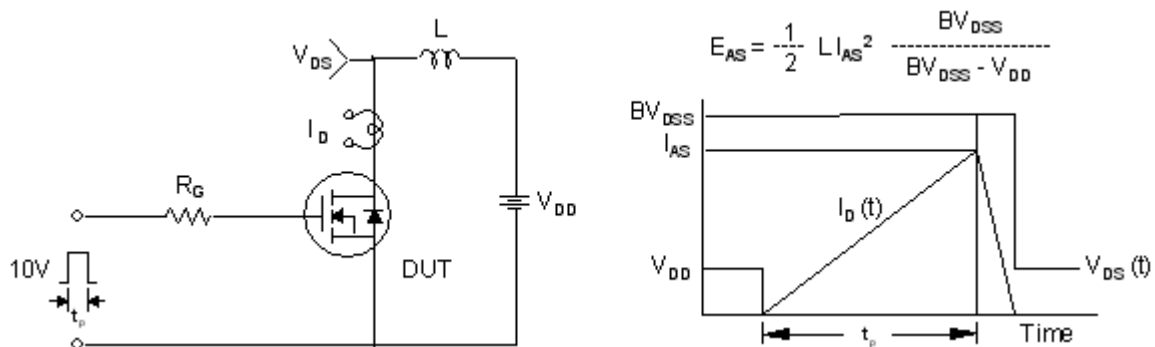
Gate Charge Test Circuit & Waveform



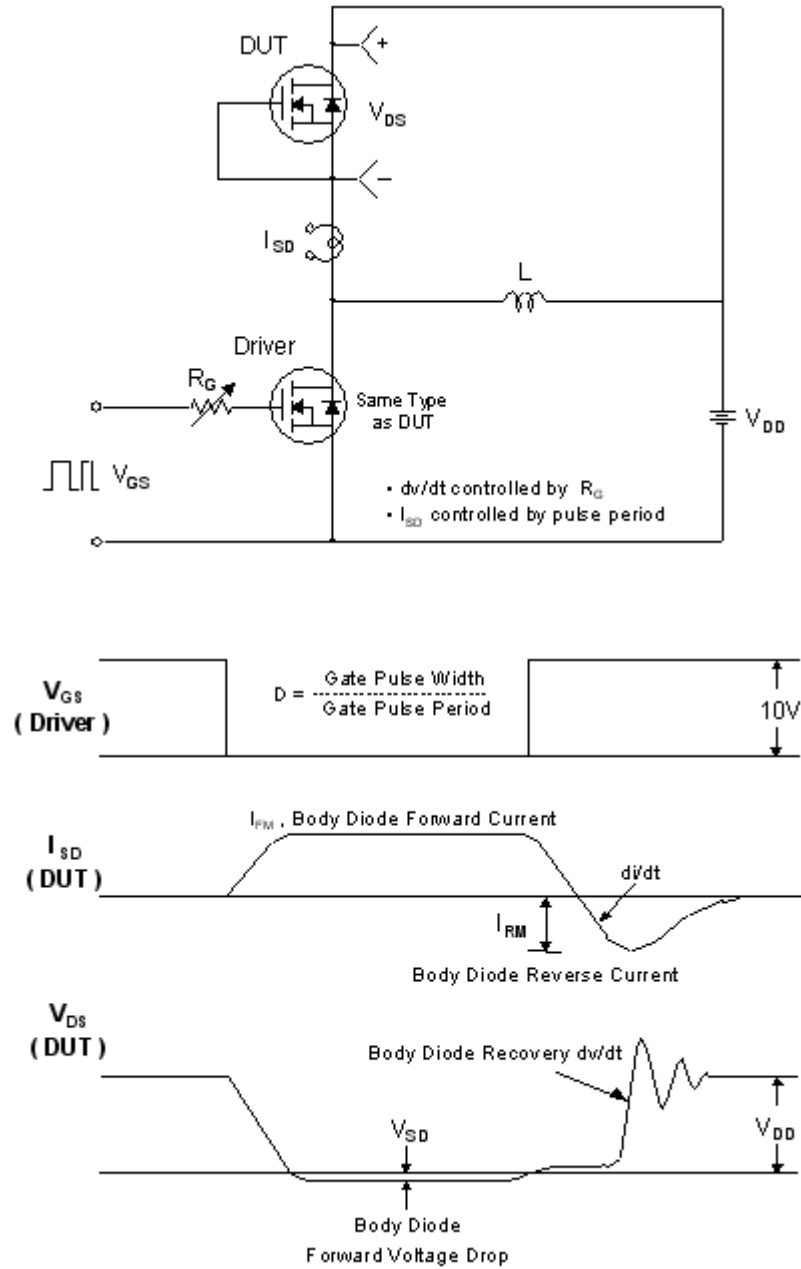
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

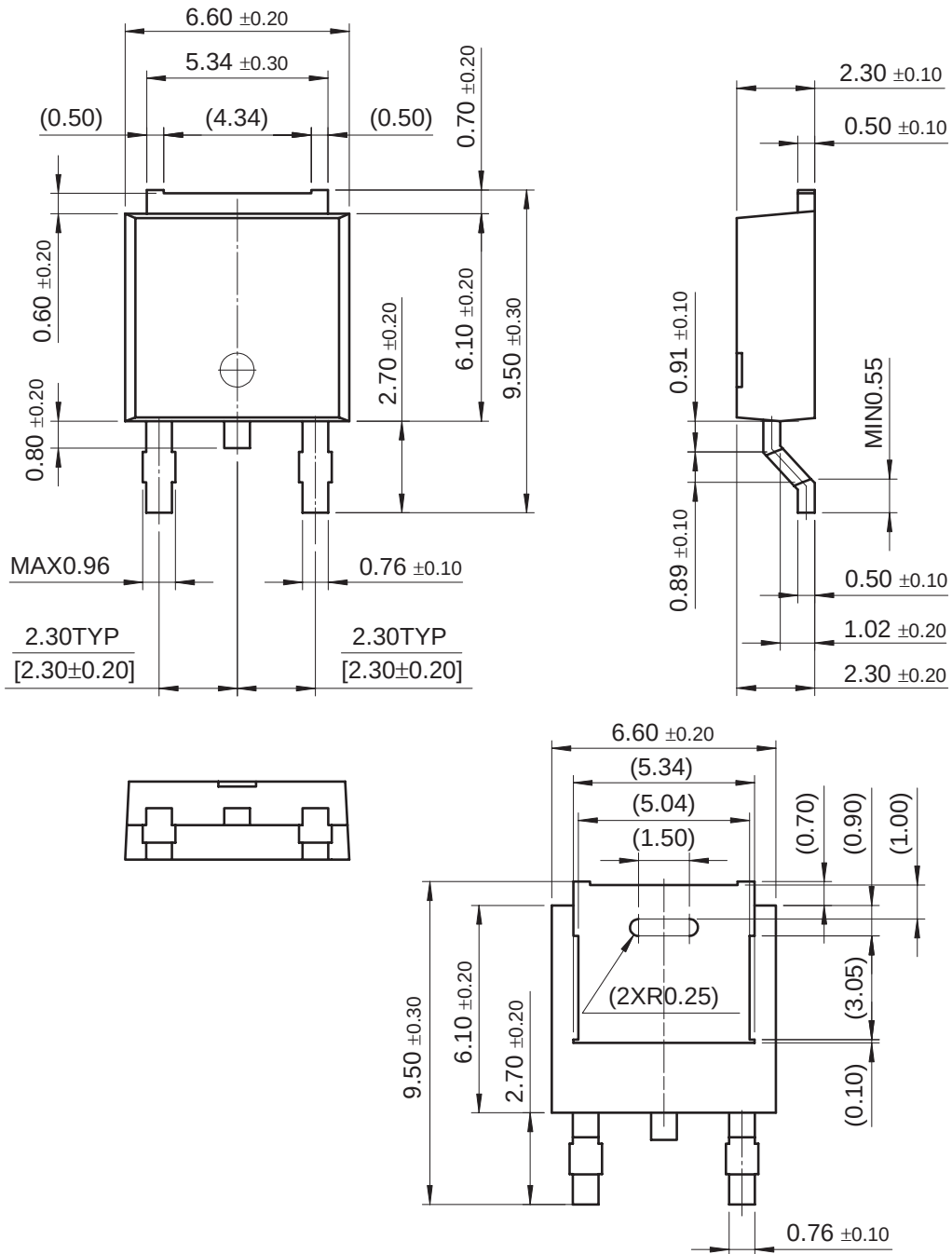


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

D-PAK



Dimensions in Millimeters

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Rev. I18